

# RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS12887 (w/BR1225)	Apr-96	9607 A2	DALLAS	DA074730AAA	N/A	24 MODULE

**STRESS/JOB NO.**

**READPOINT  
(Sample Size/No. of Fails)**

Hi Temp Storage  
85°C, No Bias  
P-17211

48 Hr      Cum %  
200/0      0.0%

Temp Cycle  
0°C to +70°C  
P-17256

300 ~    1K ~      Cum %  
100/0    100/0      0.0%

Biased Moisture  
85°C/85% RH, 5.5 V.  
P-17257

274 Hr    959 Hr      Cum %  
100/0    100/0      0.0%

Phys. Dimen.      Solderability  
P-17210      P-17209  
5/0              24/0

**Failure Mode**

**Failure Analysis**